

MiniMet® 1000

Semi-Automatic Grinder/Polisher



BUEHLER

Excellent Results. Easily Repeatable.™

Easy to Use and Versatile



The MiniMet® 1000 Grinder/Polisher is designed for low volume laboratories preparing single specimens. This semi-automatic grinder-polisher prepares a wide variety of materials using the three self contained preparation bowls and easy-to-use touch panel controls. Its space saving design employs a proprietary geometric action that combines the advantages of hand as well as mechanical polishing. This motion provides a random polishing action, eliminating any induced polishing artifacts.

Easy to Use

The MiniMet® 1000 comes with suggested programs for a wide variety of materials. The easy-to-use controls allow for selection of speed, pressure, time and soft stop capability. Just select the most appropriate method, key in the parameters and start the system. The MiniMet® 1000 completely

controls the preparation process and assures complete repeatability. The economically sized polishing bowls, 2⁷/₈" (75mm), easily interchange to eliminate cross-contamination problems between preparation steps. No operator expertise is required for obtaining quality results from day one to the next.

Quality Preparation

The fully adjustable speed and high pressure capability (2-10 lbs./10-50 N) reduces preparation time and allows the MiniMet® 1000 to easily prepare advanced ceramics, composites, and even hardened steel sections. The soft stop feature automatically reduces the sample pressure during the final polishing sequence, no hand polishing is necessary. This technique is ideal for preparation of softer materials.

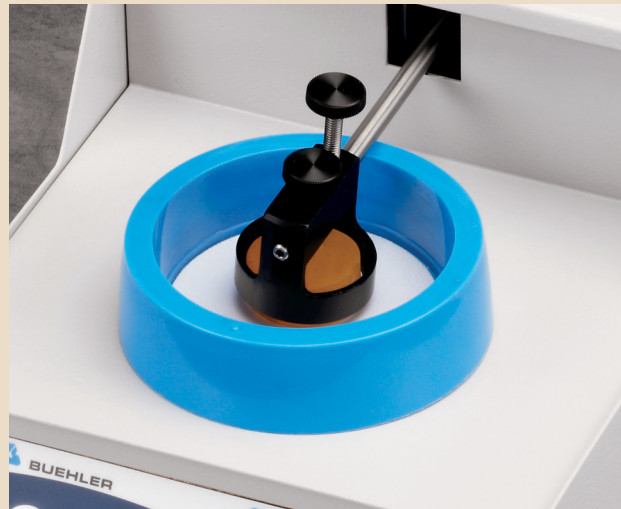
Versatile

To increase its versatility, many accessories are available for the MiniMet® 1000. Attachments for the precision thinning of materials, wafer polishing, and thin section preparation are available. The system can also utilize the latest BUEHLER SumMet® methods.

The MiniMet® 1000 offers the latest in ease-of-use, versatility, and economy for the semi-automatic preparation of all materials.



Control Panel features touch-pad controls and LED displays of all grinding/polishing parameters.



Caged Sample Holder facilitates sample preparation without the need to drill a back hole in the sample.



Thin Section Attachment is ideal for automatic preparation of glass slides and geological samples.



Precision Thinning Attachment enables SEM and TEM samples to be prepared.



The IsoMet® Low Speed Saw is an excellent companion to the MiniMet® 1000 Grinder/Polisher including when low deformation sectioning is required prior to polishing.

Product Specifications

No. 69-1100 MiniMet® Grinder/Polisher, microprocessor controlled, with on-off switch, variable load display in pounds or newtons, selectable soft stop function, variable speed control, and automatic timer. Complete with three polishing bowls (one each black, white, and blue), three glass platens, samples of CarbiMet® Paper and polishing cloth, and operating instructions. For worldwide operation on 85-264V/50-60 Hz/single phase.

Dimensions: 7"W x 16"D x 8"H (180mm x 400 mm x 200mm).

Approximate shipping weight: 25 lbs. (11kg).

Accessories

69-1111 Caged Sample Holder, for 1" (25mm) or 1¼" (32mm) mounts

69-1112 Caged Sample Holder, for 1½" (38mm) mounts

69-1500 Polishing Bowls, (set of 3) 1 each: black, white, blue, 4" (100mm)

69-1501 Polishing Bowls, (set of 3) 1 each: yellow, green, red

69-1502 Storage Caddies, (set of 3) for MiniMet® Bowls

69-1510 Glass Platens, (set of 3) for Polishing Bowls

69-1550 Sample Alignment Fixtures, with 3 drill bits

69-1552 Drill Bits, (set of 3) replacement

69-1583 MiniMet® Thin Section Slide Holder, for 27mm x 46mm slides

69-1580 Thin Section Bowls, (set of 3) 1 each: black, white, blue

69-1581 Polishing Bowls, (set of 3) 1 each: black, white, blue, 4¾" (121mm)

69-1582 Thin Section Glass Platen, (set of 3) replacement 4" (100mm)

69-1566 MiniMet® Precision Thinning Attachment, complete with upper platen with micrometer adjustment, lower platen and bearing race, Operating instructions.

69-1570 MiniMet® Electromechanical Attachment, complete with bowl, anode, and cathode connectors and 10 volt ElectroMet® Power Supply for 115V/60Hz/1 phase. Operating instructions.

69-1590 MiniMet® Wafer Polishing Attachment, with adjustable thickness control for 1" (25mm) diamond wafers. Operating instructions.



Storage Caddies for MiniMet® Bowls, Set of 3

Magnetic Backed Cloths

(5 per pack) 2-7/8" (73mm)

Ultra MB 41-10096

TexMet® MB 41-10097

Satyn MB 41-10098

Chemia MB 41-10099

Micro MB 41-10100

For a complete listing of consumables, please refer to our Consumables Buyer's Guide. Buehler continuously makes product improvements; therefore technical specifications are subject to change without notice.

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